

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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# HVD132

Silicon Epitaxial Planar Pin Diode for High Frequency Switching



ADE-208-830A (Z)

Rev. 1  
Sep. 2000

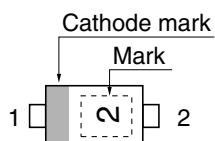
## Features

- Low capacitance. ( $C = 0.5 \text{ pF max}$ )
- Low forward resistance. ( $r_f = 2.0 \Omega \text{ max}$ )
- Super small Flat Package (SFP) is suitable for surface mount design.

## Ordering Information

Type No.	Laser Mark	Package Code
HVD132	2	SFP

## Pin Arrangement



1. Cathode  
2. Anode

## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	$V_{RM}$	65	V
Reverse voltage	$V_R$	60	V
Forward current	$I_F$	100	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	$I_R$	—	—	0.1	μA	$V_R = 60\text{ V}$
Forward voltage	$V_F$	—	—	1.0	V	$I_F = 10\text{ mA}$
Capacitance	C	—	—	0.5	pF	$V_R = 1\text{ V}$ , $f = 1\text{ MHz}$
Forward resistance	$r_i$	—	—	2.0	Ω	$I_F = 10\text{ mA}$ , $f = 100\text{ MHz}$

Note: Please do not use the soldering iron due to avoid high stress to the SFP package.

## Main Characteristic

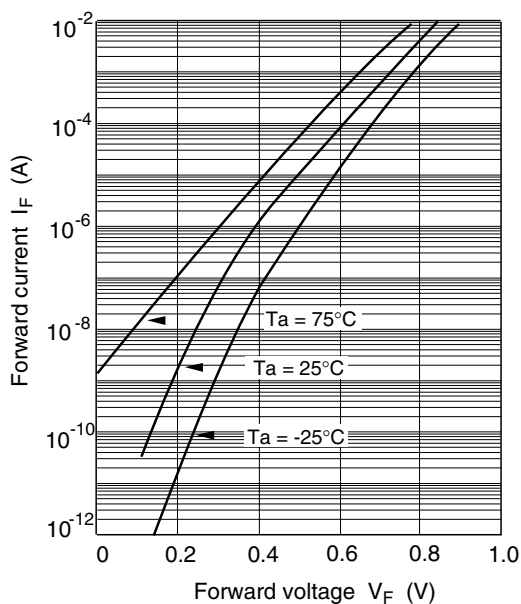


Fig.1 Forward current Vs. Forward voltage

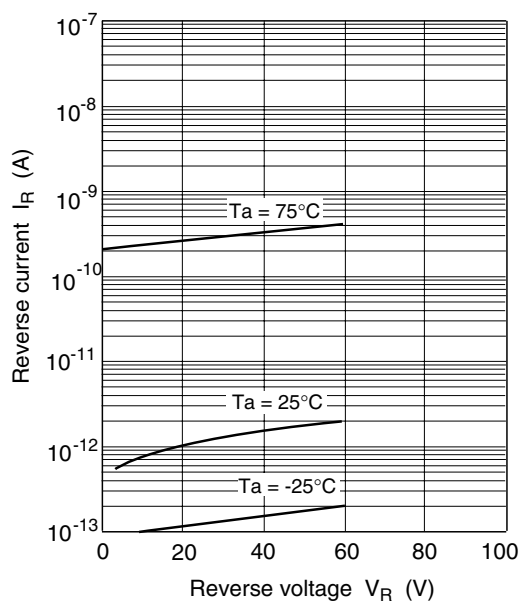


Fig.2 Reverse current Vs. Reverse voltage

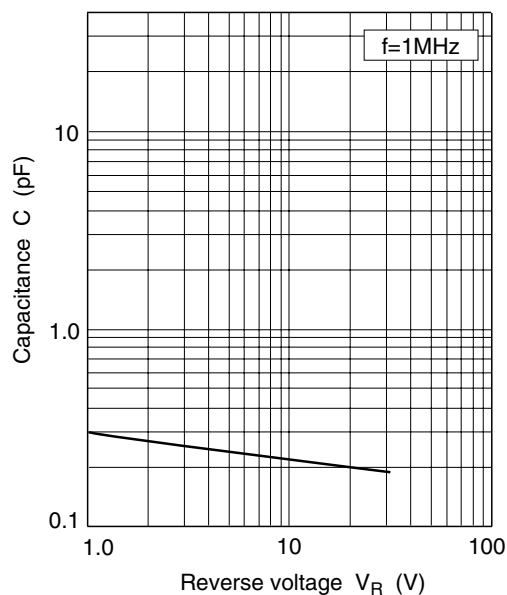


Fig.3 Capacitance Vs. Reverse voltage

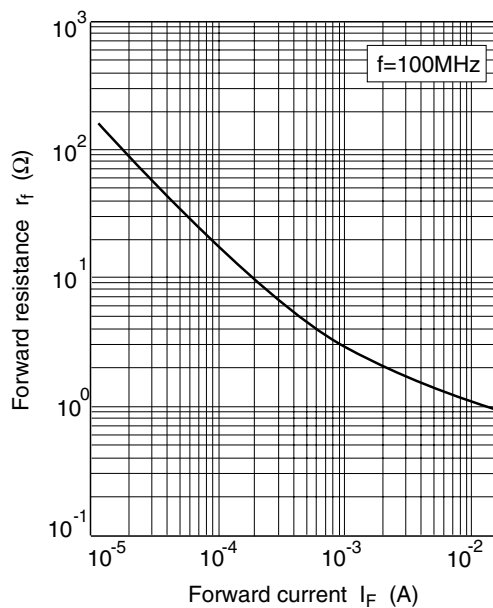
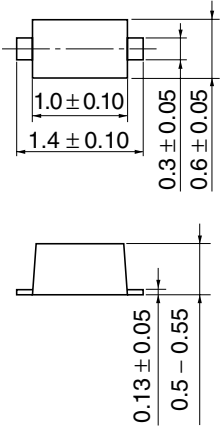


Fig.4 Forward resistance Vs. Forward current

Package Dimensions

Unit: mm



Hitachi Code	SFP
JEDEC	—
EIAJ	—
Mass (reference value)	0.0010 g

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